Customer Service Window Randolph Building 401 Dulany Street Alexandria, VA 22314

PR 2 8 2005

Atty. Docket No.: 2677-000019/US Page 1 of 1

RECORDATION FORMEROVI 05-03-2005				
To the Honorable Commissioner of Patents :				
Name of conveying party(ies):	2. Name and . 102993651			
1. Heung-Kyu KWON	Name: SAMSUNG ELECTRONICS CO., LTD.,			
2. Hee-Seok LEE	Street Address: 416 Maetan-dong, Yeongtong-gu			
Additional name(s) of conveying party(ies) attached?				
3. Nature of conveyance:	Country: Republic of KOREA			
□ Assignment □ Merger □ Security Agreement				
☐ Change of Name ☐ Other:	Additional name(s) & address(es) attached? YES NO			
Execution Date: 1. April 8, 2005 and				
2. April 8, 2005, respectively				
4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is:				
A. Patent Application No(s).	B. Patent No.(s).			
11/033,997				
Additional numbers attached? YES NO				
Name and address of party to whom correspondence concerning document should be mailed:	6. Total No. of applications/patents involved: One (1) 7. Total fee (37 C.F.R. § 3.41): \$40.00			
Name: HARNESS, DICKEY & PIERCE, P.L.C.	Enclosed			
Street Address: P.O. BOX 8910				
City: RESTON State: VA ZIP: 20195	Authorized to be charged to deposit account, if no fee attached.			
Country: USA	8. Deposit account number: <u>08-0750</u>			
{ 	(Attach triplicate copy of this page			
	if paying by deposit account)			
DO NOT USE THIS SPACE				
9. Statement and signature.				
To the best of my knowledge and belief, the follegoing in of the original document.	nformation is true and correct and any attached copy is a true copy			
John A. Castellano/35,094	April 28, 2005			
Name of Person Signing/Reg. No.	Signature Date			
Total number of pages including cover sh	eet, attachments, and document: Three (3)			

05/02/2005 ECOOPER 00000079 11033997

JAC/let

01 FC:8021

40.00 DP

PATENT REEL: 016506 FRAME: 0143

ASSIGNMENT

Atty. Docket No. 2677-000019/US

WHEREAS, the undersigned, hereinafter referred to collectively as Assignor, has invented:

A MULTI-CHIP PACKAGE, A SEMICONDUCTOR DEVICE USED THEREIN AND **MANUFACTURING METHOD THEREOF**

for whice patent	ch Assi	gnor is a	about to make or has made United States or International application for
	(a)		executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney);
	(b)		executed on,; or
	(c)	\boxtimes	filed on <u>January 13, 2005</u> , and assigned Serial No. <u>11/033,997</u> or PCT International Application No;
	(d)		U.S. Patent No, issued; and
		•	AMSUNG ELECTRONICS CO., LTD., a corporation of Korea having a siness at 416 Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do,

Republic of Korea, hereinafter referred to as Assignee, is desirous of acquiring an interest therein:

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy whereof is hereby acknowledged, Assignor by these presents does sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America and all foreign countries, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the said invention as described in the aforesaid application, said application for patent and all Letters Patent therefor to be held and enjoyed by Assignee to the full end of the term for which said Letters Patent are granted and any extensions thereof as fully and entirely as the same would have been held by Assignor had this assignment and sale not been made, and the right to recover for past infringements of, or liabilities for, any of the rights relating to any of said applications or patents resulting therefrom;

Assignor hereby covenants and agrees to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, re-examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth;

Assignor hereby covenants that no assignment, sale or agreement or encumbrance has been or will be entered into which would conflict with this Assignment; and

Assignor hereby requests the Commissioner of Patents and Trademarks to issue said Letters Patent of the United States of America to Assignee, and requests that any official of any country or countries foreign to the United States, whose duty it is to issue or grant patents and applications as a foresaid, to issue said Letters Patent, Utility Model Registration or Inventor's Certificate to Assignee.

The undersigned hereby grant(s) the law firm of Harness, Dickey & Pierce, P.L.C. the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

ASSIGNMENT

Heung - KYU KWON Heung-Kyu KWON			
Heung-Kyu KWON			
APr. 8th, 2005			
Dated			
Nee-Seok Coe			
ylle-yeole cee			
Hee-Seok LEE			
. ^			
Ath April root			
Dated			

RECORDED: 04/28/2005

Page 2 of 2

PATENT REEL: 016506 FRAME: 0145